

11. (Amended) The interconnect substrate as defined in claim 1, wherein the second portion continuously extends from the first portion.

12. (Amended) The interconnect substrate as defined in claim 1, wherein the second portion is separated from the first portion; and wherein the first and second portions are connected by the interconnect pattern.

16. (Amended) A circuit board over which is mounted the semiconductor device as defined in claim 13.

17. (Amended) An electronic instrument provided with the semiconductor device as defined in claim 13.

18. (Amended) A method of fabricating a semiconductor device, comprising the steps of: mounting at least one semiconductor chip over the interconnect substrate as defined in claim 1; and superposing the second portion on the first portion of the interconnect substrate.

19. (Amended) A method of inspecting a semiconductor device, comprising the steps of: positioning the semiconductor device as defined in claim 13 by using a plurality of end parts as positioning references; and inspecting electrical characteristics of the semiconductor device.

20. (Amended) A method of mounting a semiconductor device comprising the steps of: positioning the semiconductor device as defined in claim 13 by using a plurality of end parts as positioning references; and mounting the semiconductor device on a circuit board.

REMARKS

Claims 1-20 are pending. Claims 10-12 and 16-20 are amended to eliminate multiple dependencies. Prompt and favorable consideration on the merits is respectfully requested.